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By:

Hans-Jürgen Hacke

Date:

July 24, 2002

8/13/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hans-Jürgen Hacke et al.
Applic. No. : 09/761,594
Filed : January 16, 2001
Title : Semiconductor Device in Chip Format and
Method for Producing It
Examiner : John T. Haran
Group Art Unit : 1733

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A M E N D M E N T

S i r :

Responsive to the non-final Office action dated April 24, 2002, kindly amend the above-identified application as follows:

In the Claims:

Cancel claims ~~6-10~~.

sub 91/03
Claim 1 (amended). A semiconductor device in chip format, comprising:

a chip;